

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

- 1-9. (Cancelled)
10. (New) An electroplating apparatus, comprising:
  - a chamber configured to contain an electroplating liquid;
  - a sonic wave generator configured to generate sonic waves in a liquid within the chamber;
  - a metal bar disposed in the chamber;
  - a power supply configured to be coupled to the metal bar and to a plated body disposed in the chamber; and
  - a controller, wherein the controller is configured to activate the sonic wave generator during a cleaning cycle to cause contaminants to be removed from surfaces of a plated body disposed in the chamber, and wherein the controller is configured to activate the power supply to cause an electroplating operation to be performed after the cleaning cycle has been completed.

11. (New) The electroplating apparatus of claim 10, wherein the controller activates the power supply only after the sonic wave generator has been deactivated.
12. (New) The electroplating apparatus of claim 10, further comprising an electroplating solution disposed in the chamber.
13. (New) The electroplating apparatus of claim 12, wherein the electroplating solution includes a cationic species of the same metal as the metal bar.
14. (New) The electroplating apparatus of claim 12, wherein the sonic wave generator is configured to cause bubbles to form in the electroplating solution along surfaces of a plated body disposed in the chamber, and wherein the formation of the bubbles provides a cleaning action.
15. (New) The electroplating apparatus of claim 14, wherein the sonic wave generator is configured to cause the bubbles to repeatedly expand and contract.
16. (New) The electroplating apparatus of claim 15, wherein the sonic wave generator is configured to cause an inner pressure of the bubbles to approach 100Kpa.

17. (New) The electroplating apparatus of claim 16, wherein the sonic wave generator is configured to cause a temperature of the bubbles to become between approximately 1000K and 3000K.
18. (New) The electroplating apparatus of claim 15, wherein the sonic wave generator is configured to cause a temperature of the bubbles to become between approximately 1000K and 3000K.
19. (New) The electroplating apparatus of claim 10, wherein the sonic wave generator is disposed within the chamber.
20. (New) An electroplating apparatus, comprising:
- a sonic chamber containing a sonic wave transfer liquid;
  - a sonic wave generator configured to generate sonic waves in the sonic wave transfer liquid;
  - an electroplating chamber disposed within the sonic chamber and configured to contain an electroplating liquid;
  - a metal bar disposed in the electroplating chamber;

a power supply configured to be coupled to the metal bar and to a plated body disposed in the electroplating chamber; and

a controller, wherein the controller is configured to activate the sonic wave generator during a cleaning cycle to cause contaminants to be removed from surfaces of a plated body disposed in the electroplating chamber, wherein sonic waves in the sonic chamber are communicated to the electroplating chamber, and wherein the controller is configured to activate the power supply to cause an electroplating operation to be performed after the cleaning cycle has been completed.

21. (New) The electroplating apparatus of claim 20, wherein the controller activates the power supply only after the sonic wave generator has been deactivated.

22. (New) The electroplating apparatus of claim 20, further comprising an electroplating solution disposed in the electroplating chamber.

23. (New) The electroplating apparatus of claim 22, wherein the electroplating solution includes a cationic species of the same metal as the metal bar.

24. (New) The electroplating apparatus of claim 22, wherein the sonic wave generator is configured to cause bubbles to form in the electroplating solution along surfaces of a plated body disposed in the electroplating chamber, and wherein the formation of the bubbles provides a cleaning action.
25. (New) The electroplating apparatus of claim 24, wherein the sonic wave generator is configured to cause the bubbles to repeatedly expand and contract.
26. (New) The electroplating apparatus of claim 25, wherein the sonic wave generator is configured to cause an inner pressure of the bubbles to approach 100Kpa.
27. (New) The electroplating apparatus of claim 26, wherein the sonic wave generator is configured to cause a temperature of the bubbles to become between approximately 1000K and 3000K.
28. (New) The electroplating apparatus of claim 25, wherein the sonic wave generator is configured to cause a temperature of the bubbles to become between approximately 1000K and 3000K.

Serial No. 10/090,753  
Amdt. dated March 1, 2004  
Reply to Office Action of August 29, 2003

Docket No. HME/D-005A

29. (New) The electroplating apparatus of claim 20, wherein the sonic wave generator is disposed within the sonic chamber.